

## N-channel 650 V, 0.71 $\Omega$ typ., 5.5 A MDmesh™ M2 Power MOSFET in an IPAK package

Datasheet - production data

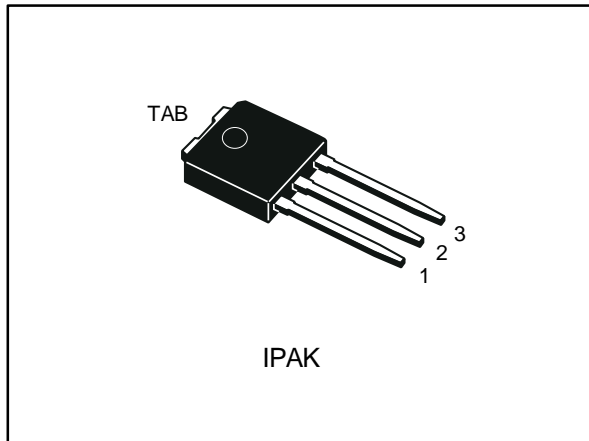
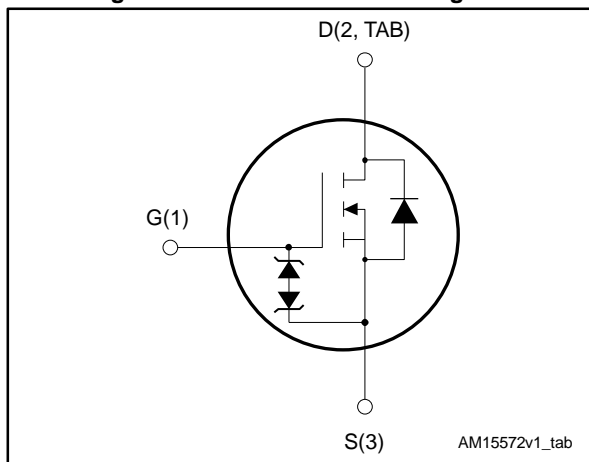


Figure 1: Internal schematic diagram



### Features

Order code	V <sub>DS</sub>	R <sub>DS(on)</sub> max.	I <sub>D</sub>
STU9HN65M2	650 V	0.82 $\Omega$	5.5 A

- Extremely low gate charge
- Excellent output capacitance (C<sub>oss</sub>) profile
- 100% avalanche tested
- Zener-protected

### Applications

- Switching applications

### Description

This device is an N-channel Power MOSFET developed using MDmesh™ M2 technology. Thanks to its strip layout and an improved vertical structure, the device exhibits low on-resistance and optimized switching characteristics, rendering it suitable for the most demanding high efficiency converters.

Table 1: Device summary

Order code	Marking	Package	Packing
STU9HN65M2	9HN65M2	IPAK	Tube

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# 1 Electrical ratings

**Table 2: Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{GS}$	Gate-source voltage	$\pm 25$	V
$I_D$	Drain current (continuous) at $T_C = 25\text{ }^\circ\text{C}$	5.5	A
$I_D$	Drain current (continuous) at $T_C = 100\text{ }^\circ\text{C}$	3.5	A
$I_{DM}^{(1)}$	Drain current (pulsed)	22	A
$P_{TOT}$	Total dissipation at $T_C = 25\text{ }^\circ\text{C}$	60	W
$dv/dt^{(2)}$	Peak diode recovery voltage slope	15	V/ns
$dv/dt^{(3)}$	MOSFET $dv/dt$ ruggedness	50	V/ns
$T_{stg}$	Storage temperature	- 55 to 150	°C
$T_j$	Max. operating junction temperature	150	

**Notes:**

(1) Pulse width limited by safe operating area.

(2)  $I_{SD} \leq 5.5\text{ A}$ ,  $di/dt \leq 400\text{ A}/\mu\text{s}$ ;  $V_{DS\ peak} < V_{(BR)DSS}$ ,  $V_{DD} = 80\% V_{(BR)DSS}$ .

(3)  $V_{DS} \leq 520\text{ V}$

**Table 3: Thermal data**

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case max.	<b>2.08</b>	°C/W
$R_{thj-amb}$	Thermal resistance junction-ambient max.	100	°C/W

**Table 4: Avalanche characteristics**

Symbol	Parameter	Value	Unit
$I_{AR}$	Avalanche current, repetitive or not repetitive (pulse width limited by $T_{jmax}$ )	<b>1.0</b>	A
$E_{AS}$	Single pulse avalanche energy (starting $T_j = 25\text{ }^\circ\text{C}$ , $I_D = I_{AR}$ , $V_{DD} = 50\text{ V}$ )	105	mJ

## 2 Electrical characteristics

(T<sub>C</sub> = 25 °C unless otherwise specified).

**Table 5: Static**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V <sub>(BR)DSS</sub>	Drain-source breakdown voltage	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 1 mA	650			V
I <sub>DSS</sub>	Zero gate voltage drain current	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 650 V			1	μA
		V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 650 V, T <sub>C</sub> = 125 °C			100	μA
I <sub>GSS</sub>	Gate-body leakage current	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ±25 V			±10	μA
V <sub>GS(th)</sub>	Gate threshold voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA	2	3	4	V
R <sub>DS(on)</sub>	Static drain-source on-resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 2.5 A		0.71	0.82	Ω

**Table 6: Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C <sub>iss</sub>	Input capacitance	V <sub>DS</sub> = 100 V, f = 1 MHz, V <sub>GS</sub> = 0 V	-	325	-	pF
C <sub>oss</sub>	Output capacitance		-	16	-	pF
C <sub>rss</sub>	Reverse transfer capacitance		-	0.85	-	pF
C <sub>oss eq. (1)</sub>	Equivalent output capacitance	V <sub>DS</sub> = 0 V to 520 V, V <sub>GS</sub> = 0 V	-	109	-	pF
R <sub>G</sub>	Intrinsic gate resistance	f = 1 MHz open drain	-	5.6	-	Ω
Q <sub>g</sub>	Total gate charge	V <sub>DD</sub> = 520 V, I <sub>D</sub> = 5 A, V <sub>GS</sub> = 10 V (see <a href="#">Figure 15: "Test circuit for gate charge behavior"</a> )	-	11.5	-	nC
Q <sub>gs</sub>	Gate-source charge		-	2.5	-	nC
Q <sub>gd</sub>	Gate-drain charge		-	5	-	nC

**Notes:**

(1) C<sub>oss eq.</sub> is defined as a constant equivalent capacitance giving the same charging time as C<sub>oss</sub> when V<sub>DS</sub> increases from 0 to 80% V<sub>DSS</sub>.

**Table 7: Switching times**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
t <sub>d(on)</sub>	Turn-on delay time	V <sub>DD</sub> = 325 V, I <sub>D</sub> = 2.5 A R <sub>G</sub> = 4.7 Ω, V <sub>GS</sub> = 10 V (see <a href="#">Figure 14: "Test circuit for resistive load switching times"</a> and <a href="#">Figure 19: "Switching time waveform"</a> )	-	7.5	-	ns
t <sub>r</sub>	Rise time		-	4.6	-	ns
t <sub>d(off)</sub>	Turn-off-delay time		-	24	-	ns
t <sub>f</sub>	Fall time		-	14.5	-	ns

Table 8: Source-drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}$	Source-drain current		-		5.5	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		22	A
$V_{SD}^{(2)}$	Forward on voltage	$V_{GS} = 0\text{ V}$ , $I_{SD} = 5\text{ A}$	-		1.6	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 5\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$ , $V_{DD} = 60\text{ V}$ (see <a href="#">Figure 16: "Test circuit for inductive load switching and diode recovery times"</a> )	-	268		ns
$Q_{rr}$	Reverse recovery charge		-	1.7		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current		-	12.5		A
$t_{rr}$	Reverse recovery time	$I_{SD} = 5\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$ , $V_{DD} = 60\text{ V}$ , $T_j = 150\text{ }^\circ\text{C}$ (see <a href="#">Figure 16: "Test circuit for inductive load switching and diode recovery times"</a> )	-	408		ns
$Q_{rr}$	Reverse recovery charge		-	2.6		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current		-	13		A

**Notes:**

(1) Pulse width is limited by safe operating area.

(2) Pulse test: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%.

2.1 Electrical characteristics (curves)

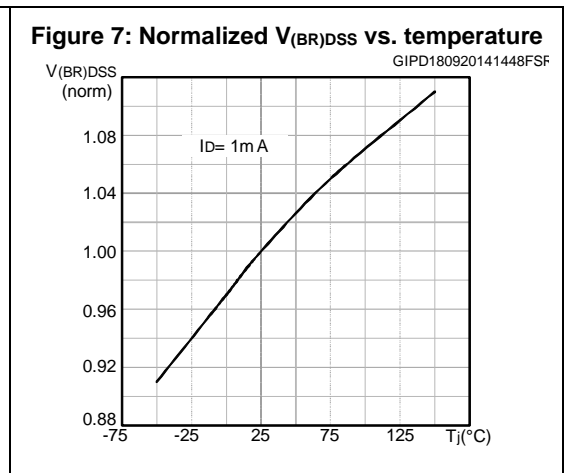
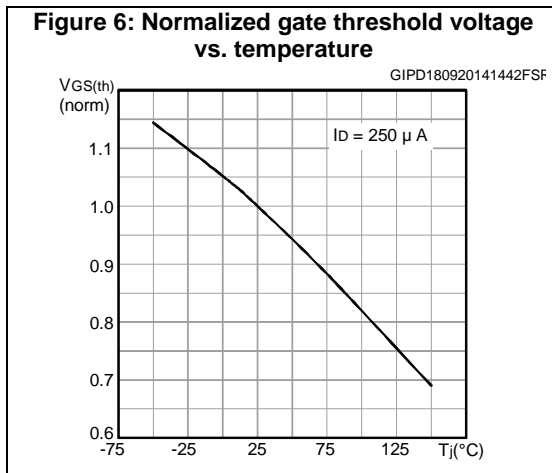
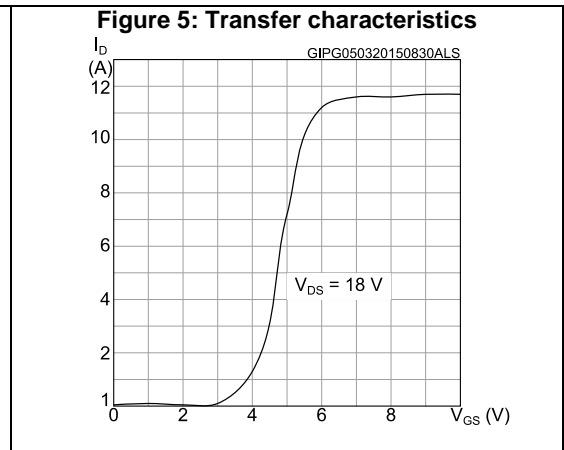
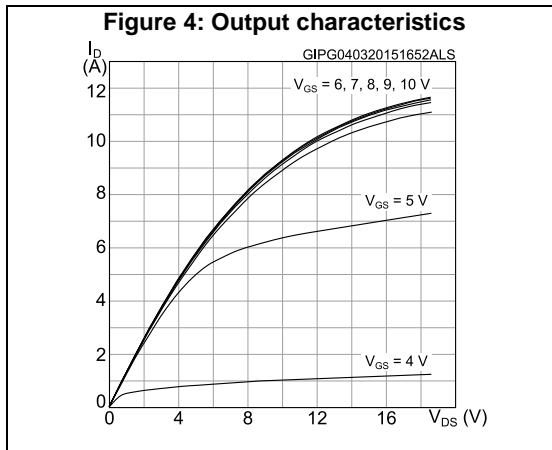
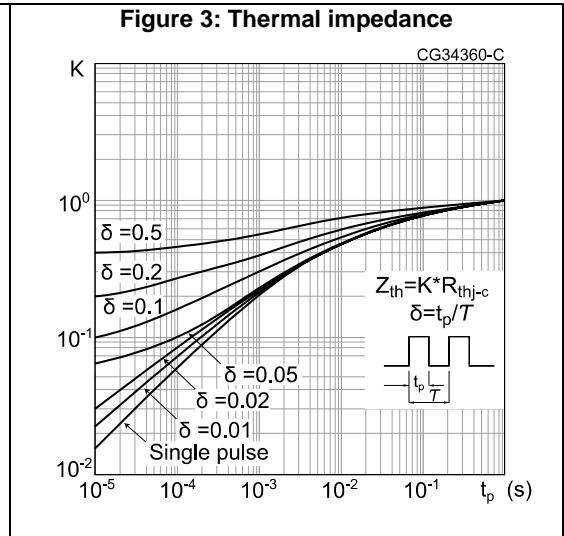
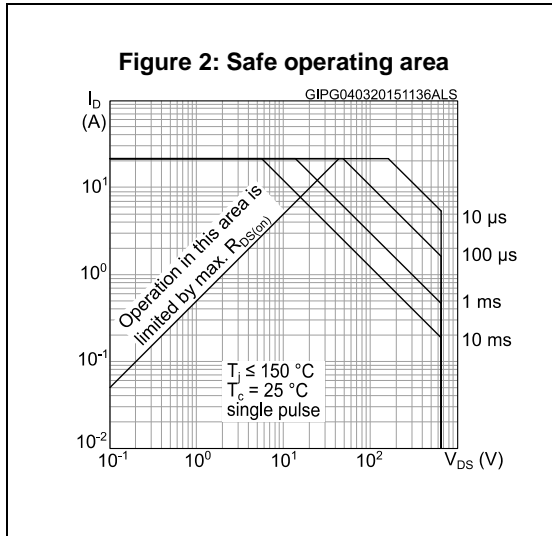


Figure 8: Static drain-source on-resistance

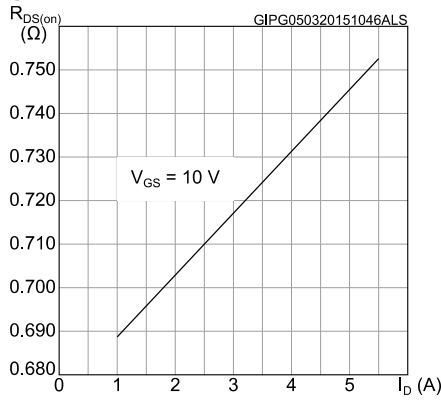


Figure 9: Normalized on-resistance vs. temperature

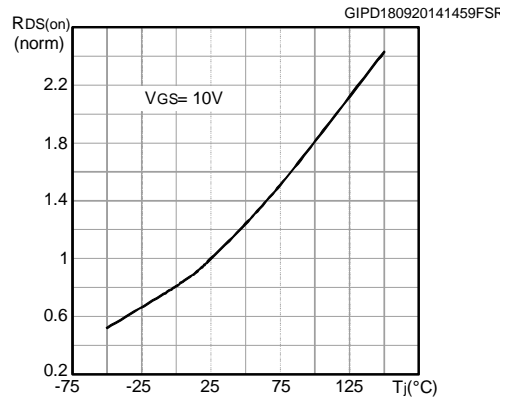


Figure 10: Gate charge vs. gate-source voltage

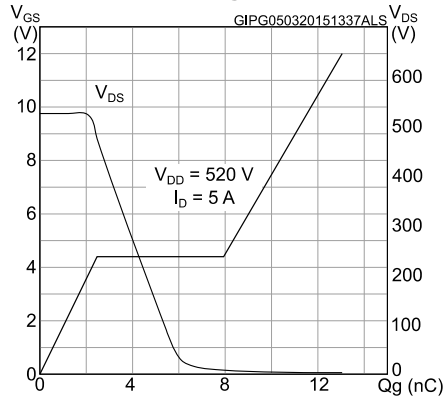


Figure 11: Capacitance variations

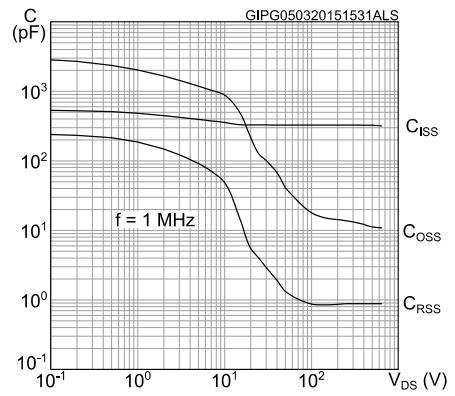


Figure 12: Output capacitance stored energy

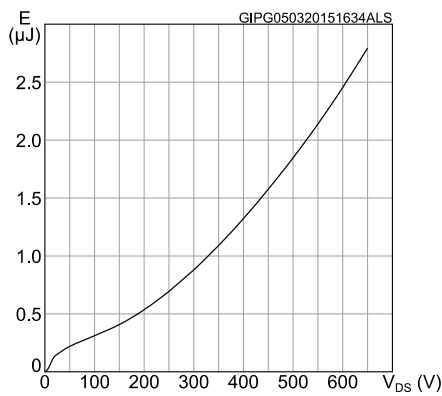
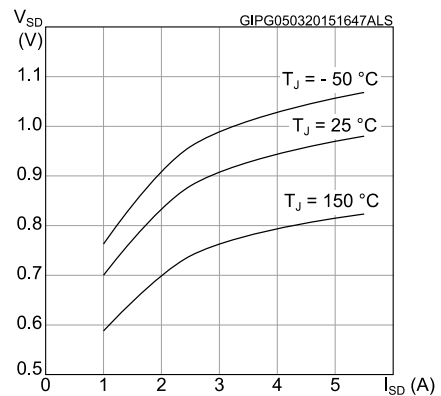
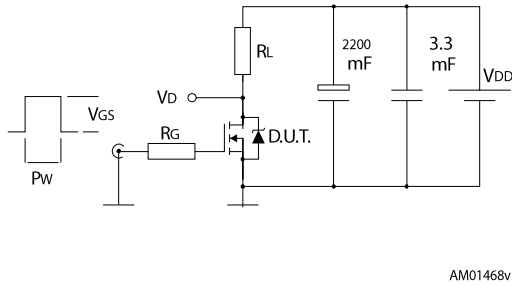


Figure 13: Source-drain diode forward characteristics



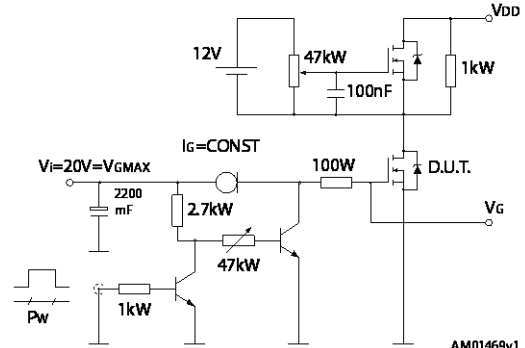
### 3 Test circuits

**Figure 14: Test circuit for resistive load switching times**



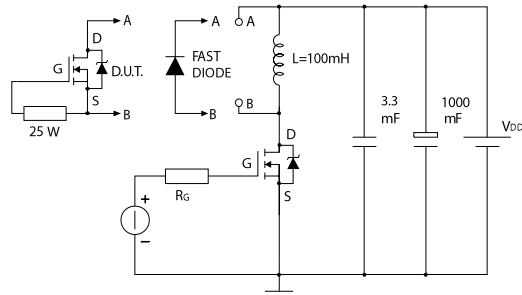
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**Figure 15: Test circuit for gate charge behavior**



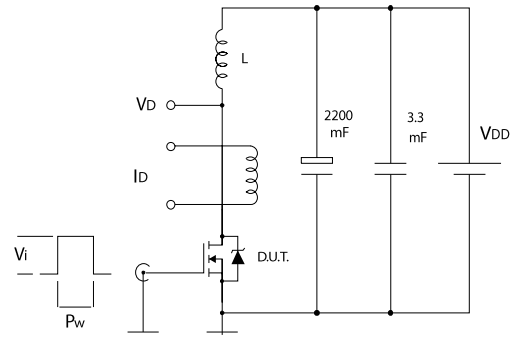
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**Figure 16: Test circuit for inductive load switching and diode recovery times**



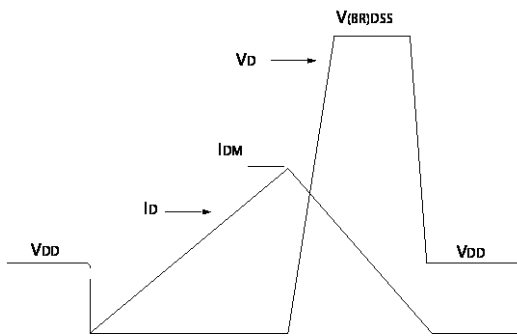
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**Figure 17: Unclamped inductive load test circuit**



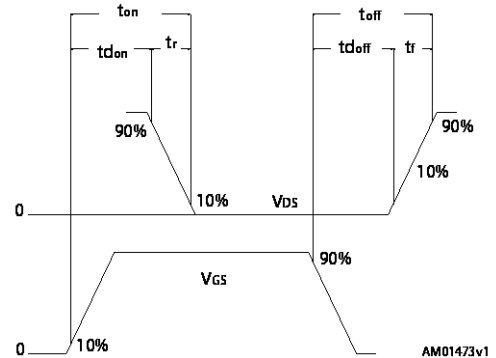
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**Figure 18: Unclamped inductive waveform**



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**Figure 19: Switching time waveform**



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## 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK® is an ST trademark.

### 4.1 IPAK (TO-251) type A package information

Figure 20: IPAK (TO-251) type A package outline

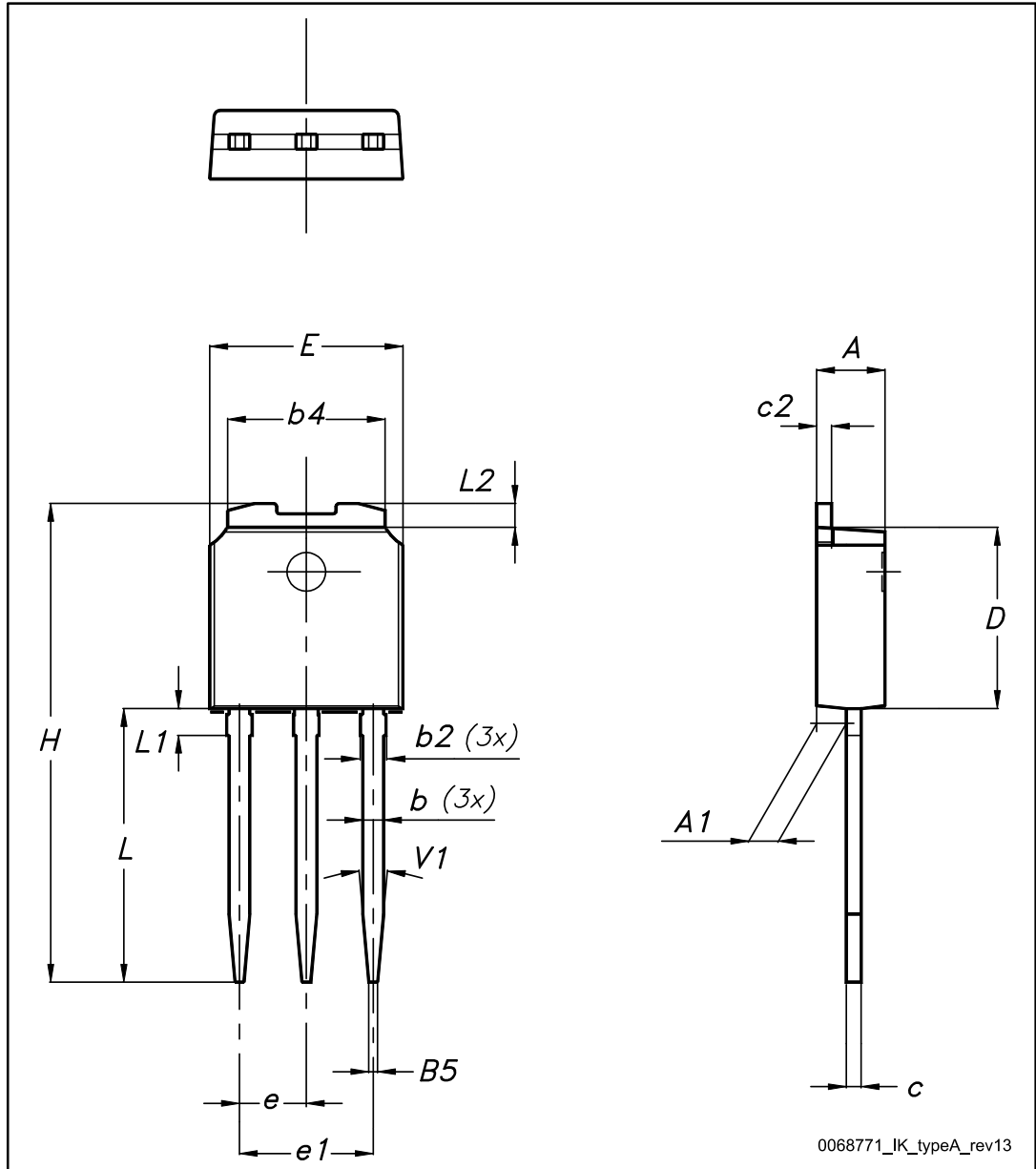


Table 9: IPAK (TO-251) type A package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	2.20		2.40
A1	0.90		1.10
b	0.64		0.90
b2			0.95
b4	5.20		5.40
B5		0.30	
c	0.45		0.60
c2	0.48		0.60
D	6.00		6.20
E	6.40		6.60
e		2.28	
e1	4.40		4.60
H		16.10	
L	9.00		9.40
L1	0.80		1.20
L2		0.80	1.00
V1		10°	

## 5 Revision history

Table 10: Document revision history

Date	Revision	Changes
11-Mar-2015	1	Initial release.
23-Apr-2015	2	Document status promoted to 'Production data'.
05-Oct-2015	3	Updated the title and changed $V_{DS}$ parameter in the table of features.

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